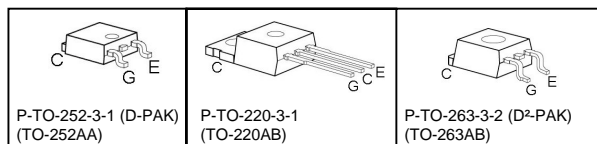
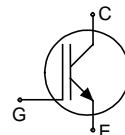


## Fast IGBT in NPT-technology

- 75% lower  $E_{off}$  compared to previous generation combined with low conduction losses
- Short circuit withstand time – 10  $\mu$ s
- Designed for:
  - Motor controls
  - Inverter
- NPT-Technology for 600V applications offers:
  - very tight parameter distribution
  - high ruggedness, temperature stable behaviour
  - parallel switching capability



- Complete product spectrum and PSpice Models : <http://www.infineon.com/igbt/>

Type	$V_{CE}$	$I_C$	$V_{CE(sat)}$	$T_j$	Package	Ordering Code
SGP02N60	600V	2A	2.2V	150°C	TO-220AB	Q67040-S4504
SGB02N60					TO-263AB	Q67040-S4505
SGD02N60					TO-252AA(DPAK)	Q67041-A4707

### Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CE}$	600	V
DC collector current	$I_C$	6.0	A
$T_C = 25^\circ\text{C}$		2.9	
$T_C = 100^\circ\text{C}$			
Pulsed collector current, $t_p$ limited by $T_{jmax}$	$I_{Cpuls}$	12	
Turn off safe operating area	-	12	
$V_{CE} \leq 600\text{V}, T_j \leq 150^\circ\text{C}$			
Gate-emitter voltage	$V_{GE}$	$\pm 20$	V
Avalanche energy, single pulse	$E_{AS}$	13	mJ
$I_C = 2\text{ A}, V_{CC} = 50\text{ V}, R_{GE} = 25\ \Omega,$ start at $T_j = 25^\circ\text{C}$			
Short circuit withstand time <sup>1)</sup>	$t_{SC}$	10	$\mu$ s
$V_{GE} = 15\text{V}, V_{CC} \leq 600\text{V}, T_j \leq 150^\circ\text{C}$			
Power dissipation	$P_{tot}$	30	W
$T_C = 25^\circ\text{C}$			
Operating junction and storage temperature	$T_j, T_{stg}$	-55...+150	°C

<sup>1)</sup> Allowed number of short circuits: <1000; time between short circuits: >1s.

## Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
<b>Characteristic</b>				
IGBT thermal resistance, junction – case	$R_{thJC}$		4.2	K/W
Thermal resistance, junction – ambient	$R_{thJA}$	TO-220AB	62	
SMD version, device on PCB <sup>1)</sup>	$R_{thJA}$	TO-252AA TO-263AB	50 40	

## Electrical Characteristic, at $T_j = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	Typ.	max.	
<b>Static Characteristic</b>						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=500\mu A$	600	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C=2A$ $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	1.7 -	1.9 2.2	2.4 2.7	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=150\mu A, V_{CE}=V_{GE}$	3	4	5	
Zero gate voltage collector current	$I_{CES}$	$V_{CE}=600V, V_{GE}=0V$ $T_j=25^\circ\text{C}$ $T_j=150^\circ\text{C}$	- -	- -	20 250	$\mu A$
Gate-emitter leakage current	$I_{GES}$	$V_{CE}=0V, V_{GE}=20V$	-	-	100	
Transconductance	$g_{fs}$	$V_{CE}=20V, I_C=2A$	-	1.6	-	S
<b>Dynamic Characteristic</b>						
Input capacitance	$C_{iss}$	$V_{CE}=25V,$ $V_{GE}=0V,$ $f=1\text{MHz}$	-	142	170	pF
Output capacitance	$C_{oss}$		-	18	22	
Reverse transfer capacitance	$C_{rss}$		-	10	12	
Gate charge	$Q_{Gate}$	$V_{CC}=480V, I_C=2A$ $V_{GE}=15V$	-	14	18	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	$L_E$	TO-220AB	-	7	-	nH
Short circuit collector current <sup>2)</sup>	$I_{C(SC)}$	$V_{GE}=15V, t_{SC}\leq 10\mu s$ $V_{CC}\leq 600V,$ $T_j\leq 150^\circ\text{C}$	-	20	-	A

<sup>1)</sup> Device on 50mm\*50mm\*1.5mm epoxy PCB FR4 with 6cm<sup>2</sup> (one layer, 70μm thick) copper area for collector connection. PCB is vertical without blown air.

<sup>2)</sup> Allowed number of short circuits: <1000; time between short circuits: >1s.

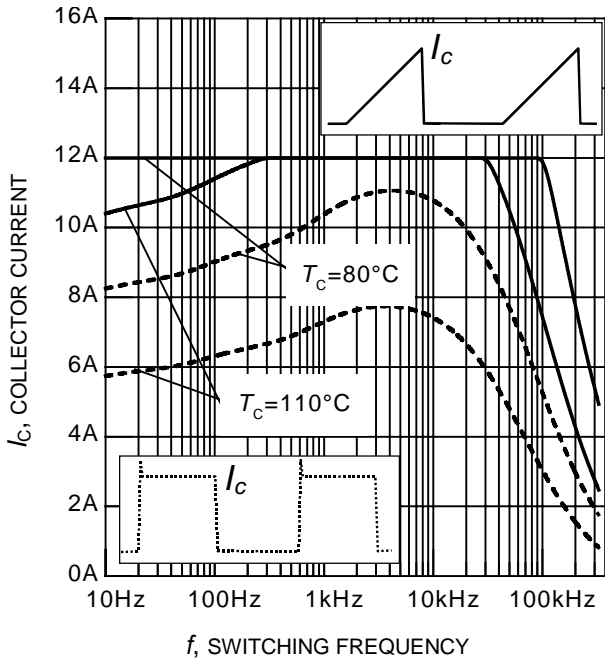
### Switching Characteristic, Inductive Load, at $T_j=25^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>IGBT Characteristic</b>						
Turn-on delay time	$t_{d(on)}$	$T_j=25^\circ\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=2\text{A}$ , $V_{GE}=0/15\text{V}$ , $R_G=118\Omega$ , $L_{\sigma}^{1)}=180\text{nH}$ , $C_{\sigma}^{1)}=180\text{pF}$ Energy losses include "tail" and diode reverse recovery.	-	20	24	ns
Rise time	$t_r$		-	13	16	
Turn-off delay time	$t_{d(off)}$		-	259	311	
Fall time	$t_f$		-	52	62	
Turn-on energy	$E_{on}$		-	0.036	0.041	mJ
Turn-off energy	$E_{off}$		-	0.028	0.036	
Total switching energy	$E_{ts}$		-	0.064	0.078	

### Switching Characteristic, Inductive Load, at $T_j=150^\circ\text{C}$

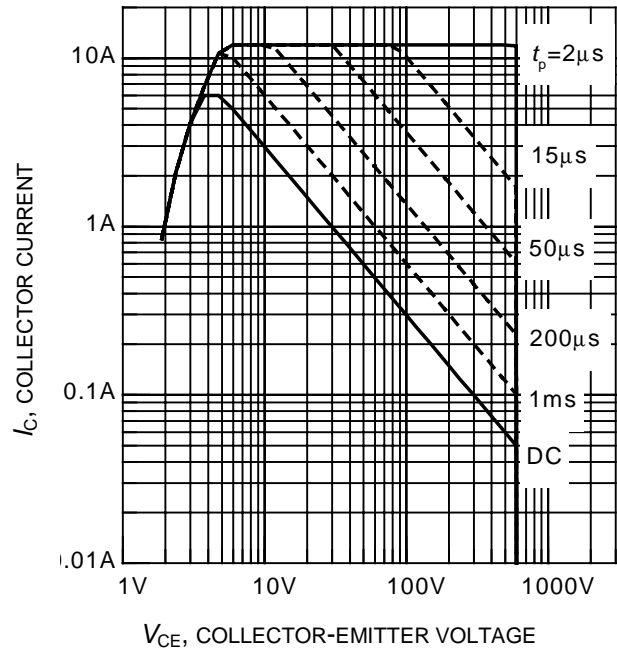
Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
<b>IGBT Characteristic</b>						
Turn-on delay time	$t_{d(on)}$	$T_j=150^\circ\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=2\text{A}$ , $V_{GE}=0/15\text{V}$ , $R_G=118\Omega$ , $L_{\sigma}^{1)}=180\text{nH}$ , $C_{\sigma}^{1)}=180\text{pF}$ Energy losses include "tail" and diode reverse recovery.	-	20	24	ns
Rise time	$t_r$		-	14	17	
Turn-off delay time	$t_{d(off)}$		-	287	344	
Fall time	$t_f$		-	67	80	
Turn-on energy	$E_{on}$		-	0.054	0.062	mJ
Turn-off energy	$E_{off}$		-	0.043	0.056	
Total switching energy	$E_{ts}$		-	0.097	0.118	

<sup>1)</sup> Leakage inductance  $L_{\sigma}$  and Stray capacity  $C_{\sigma}$  due to dynamic test circuit in Figure E.

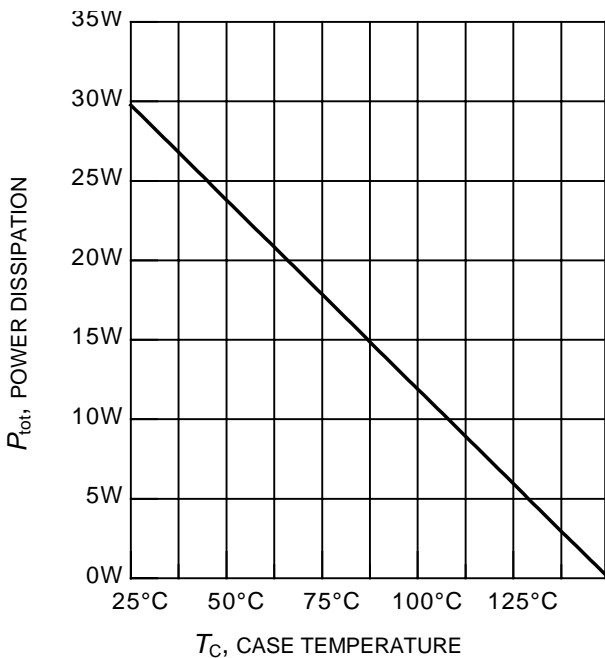


**Figure 1. Collector current as a function of switching frequency**

( $T_j \leq 150^\circ\text{C}$ ,  $D = 0.5$ ,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/+15\text{V}$ ,  $R_G = 118\Omega$ )

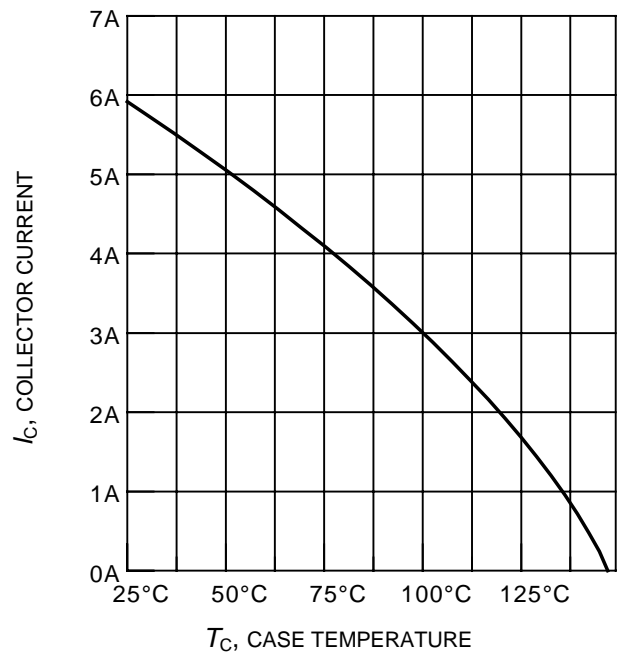


**Figure 2. Safe operating area**  
( $D = 0$ ,  $T_C = 25^\circ\text{C}$ ,  $T_j \leq 150^\circ\text{C}$ )



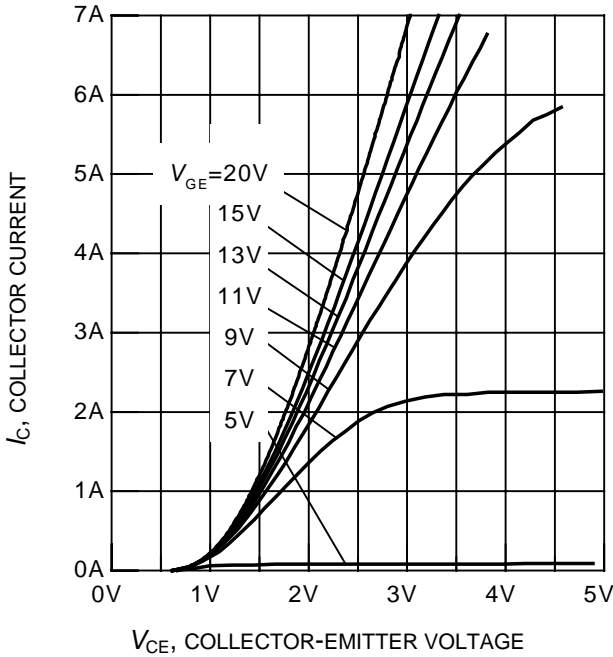
**Figure 3. Power dissipation (IGBT) as a function of case temperature**

( $T_j \leq 150^\circ\text{C}$ )

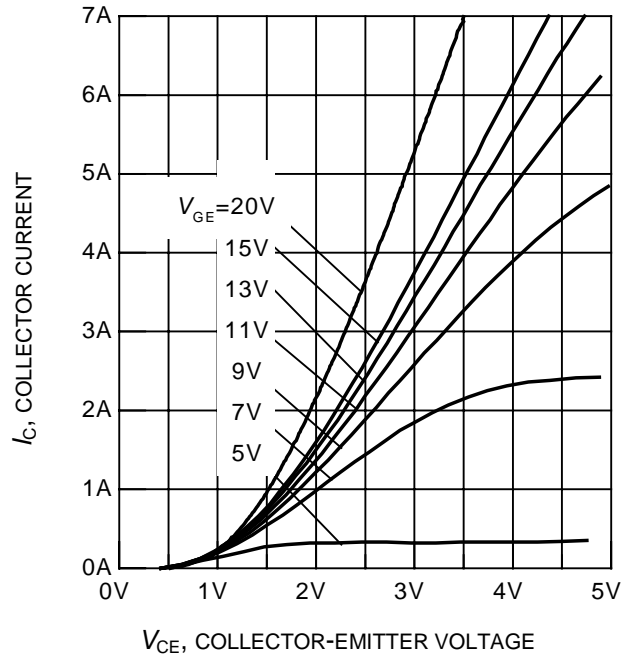


**Figure 4. Collector current as a function of case temperature**

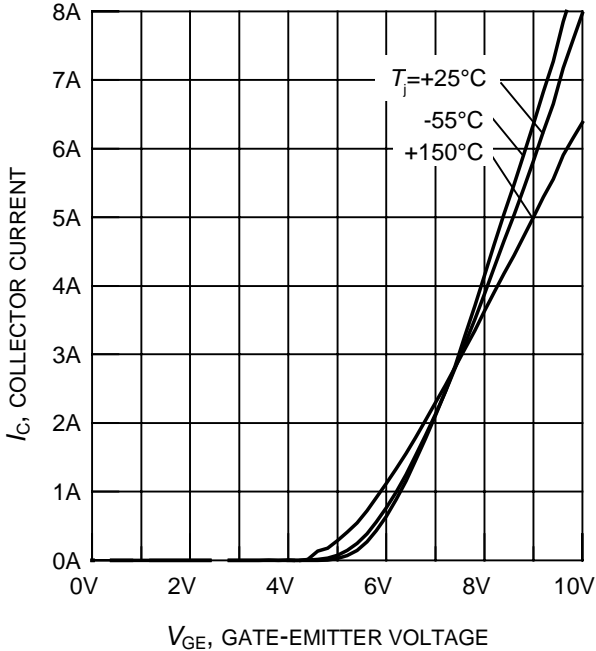
( $V_{GE} \leq 15\text{V}$ ,  $T_j \leq 150^\circ\text{C}$ )



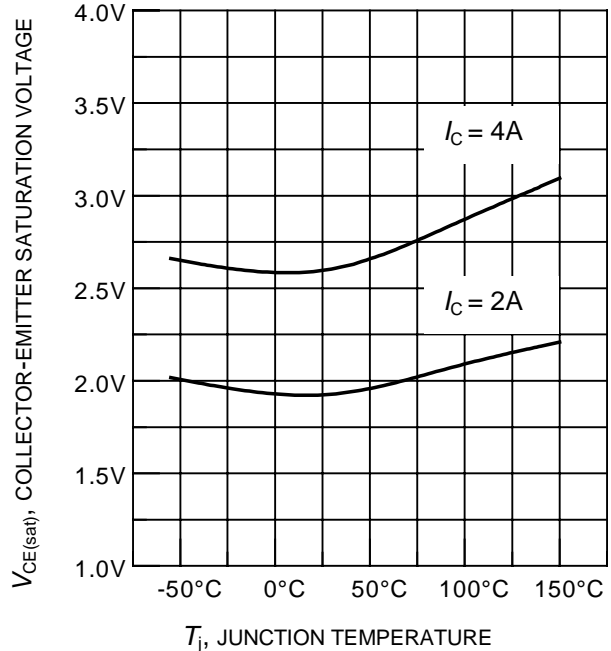
**Figure 5. Typical output characteristics**  
( $T_j = 25^\circ\text{C}$ )



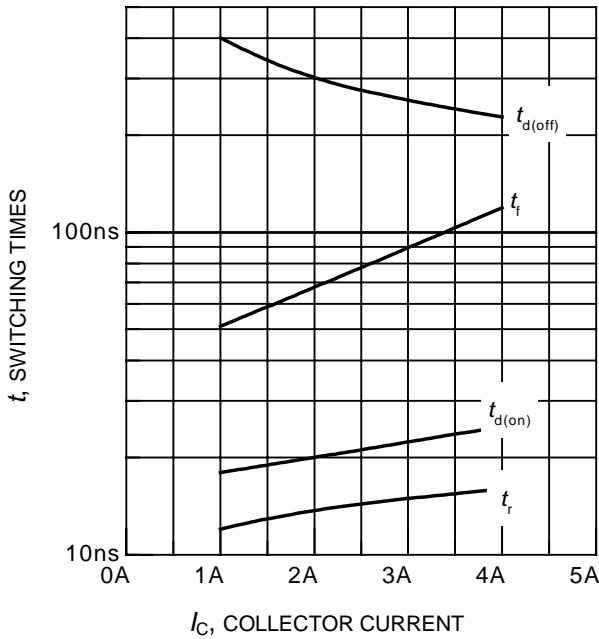
**Figure 6. Typical output characteristics**  
( $T_j = 150^\circ\text{C}$ )



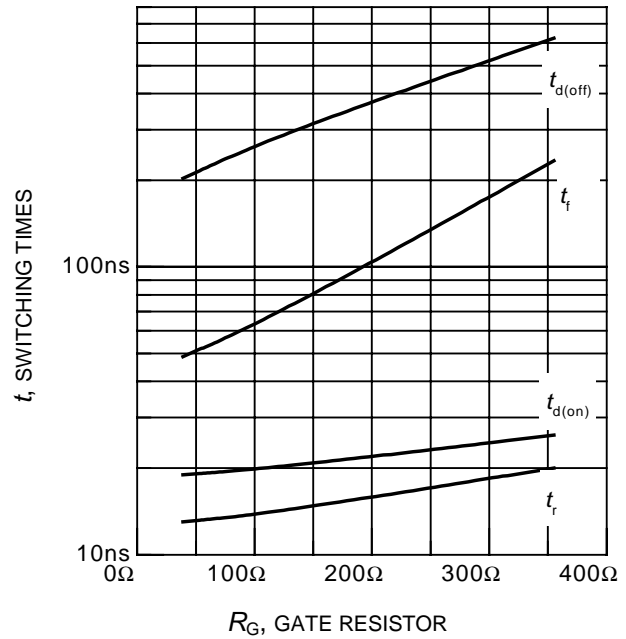
**Figure 7. Typical transfer characteristics**  
( $V_{CE} = 10\text{V}$ )



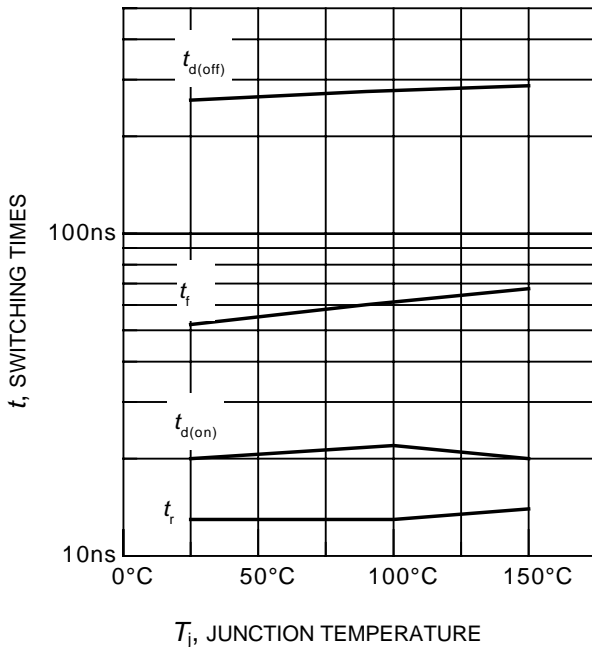
**Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature**  
( $V_{GE} = 15\text{V}$ )



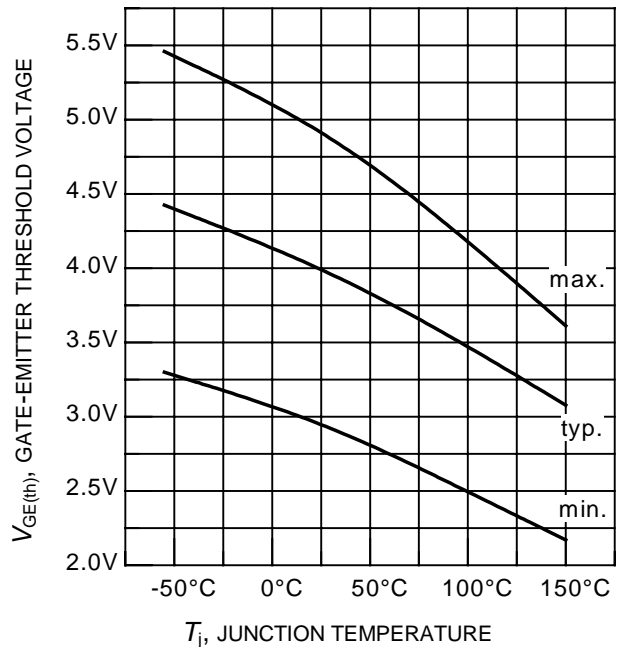
**Figure 9. Typical switching times as a function of collector current**  
(inductive load,  $T_j = 150^\circ\text{C}$ ,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/+15\text{V}$ ,  $R_G = 118\Omega$ , Dynamic test circuit in Figure E)



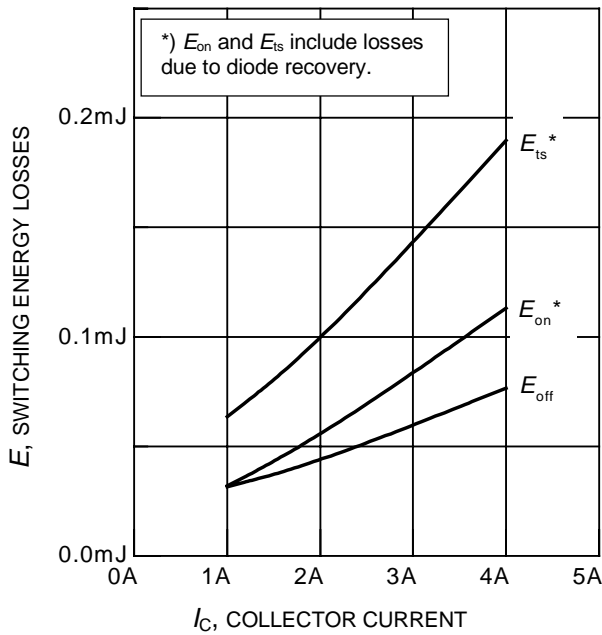
**Figure 10. Typical switching times as a function of gate resistor**  
(inductive load,  $T_j = 150^\circ\text{C}$ ,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/+15\text{V}$ ,  $I_C = 2\text{A}$ , Dynamic test circuit in Figure E)



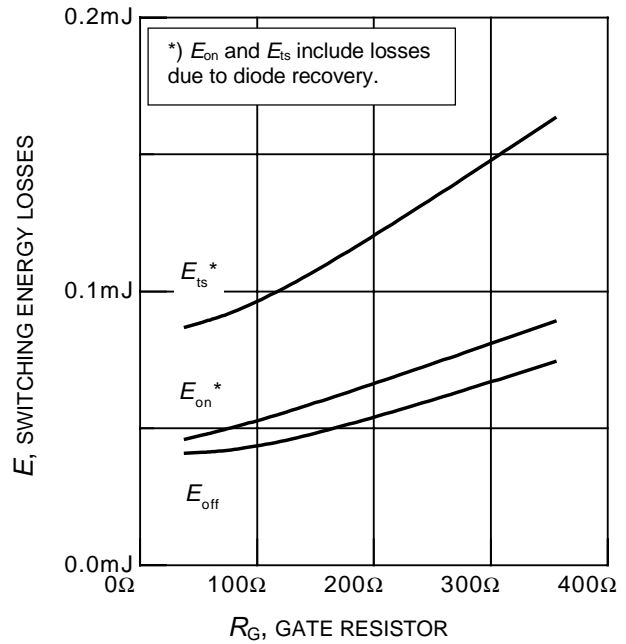
**Figure 11. Typical switching times as a function of junction temperature**  
(inductive load,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/+15\text{V}$ ,  $I_C = 2\text{A}$ ,  $R_G = 118\Omega$ , Dynamic test circuit in Figure E)



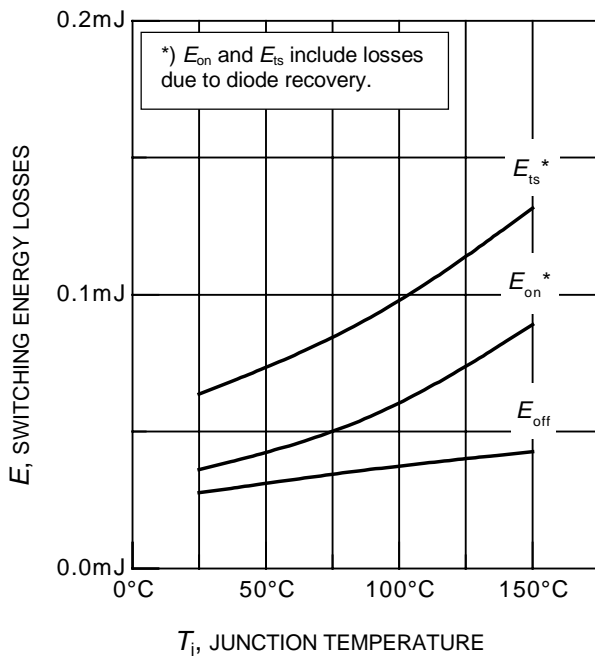
**Figure 12. Gate-emitter threshold voltage as a function of junction temperature**  
( $I_C = 0.15\text{mA}$ )



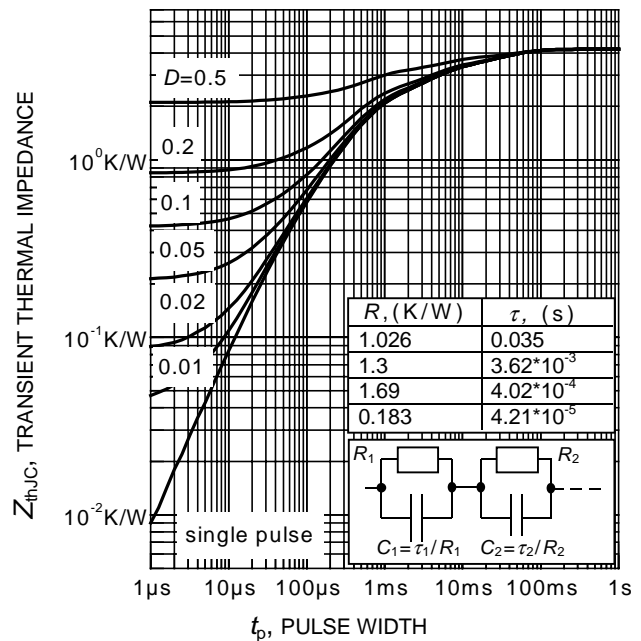
**Figure 13. Typical switching energy losses as a function of collector current**  
(inductive load,  $T_j = 150^\circ\text{C}$ ,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/+15\text{V}$ ,  $R_G = 118\Omega$ , Dynamic test circuit in Figure E)



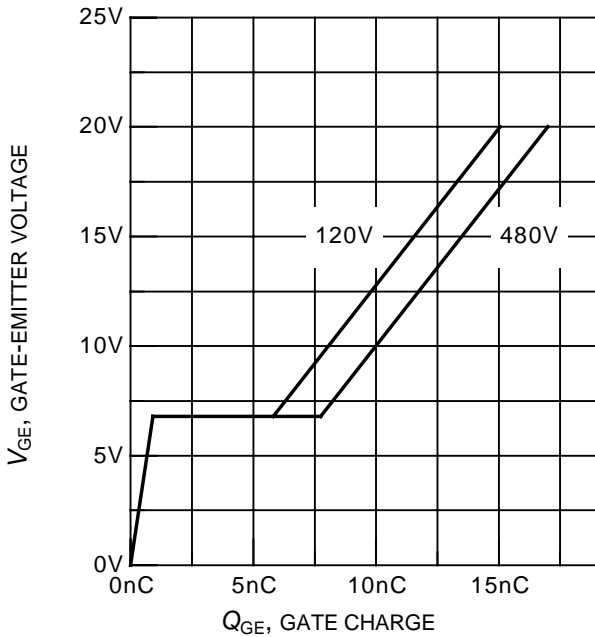
**Figure 14. Typical switching energy losses as a function of gate resistor**  
(inductive load,  $T_j = 150^\circ\text{C}$ ,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/+15\text{V}$ ,  $I_C = 2\text{A}$ , Dynamic test circuit in Figure E)



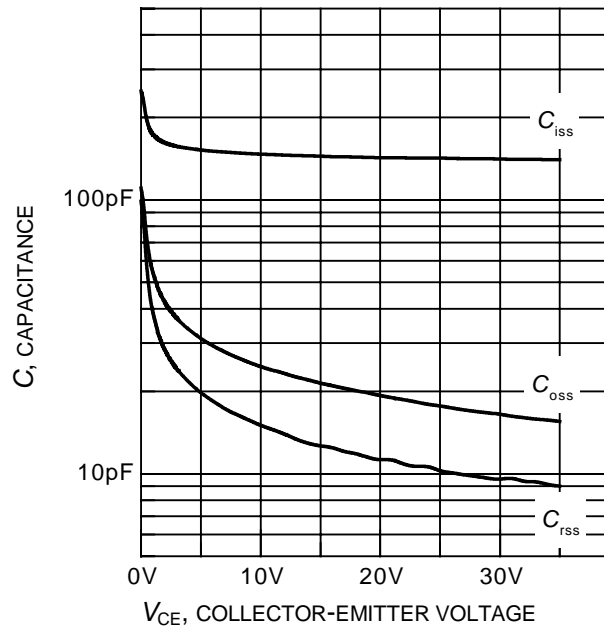
**Figure 15. Typical switching energy losses as a function of junction temperature**  
(inductive load,  $V_{CE} = 400\text{V}$ ,  $V_{GE} = 0/+15\text{V}$ ,  $I_C = 2\text{A}$ ,  $R_G = 118\Omega$ , Dynamic test circuit in Figure E)



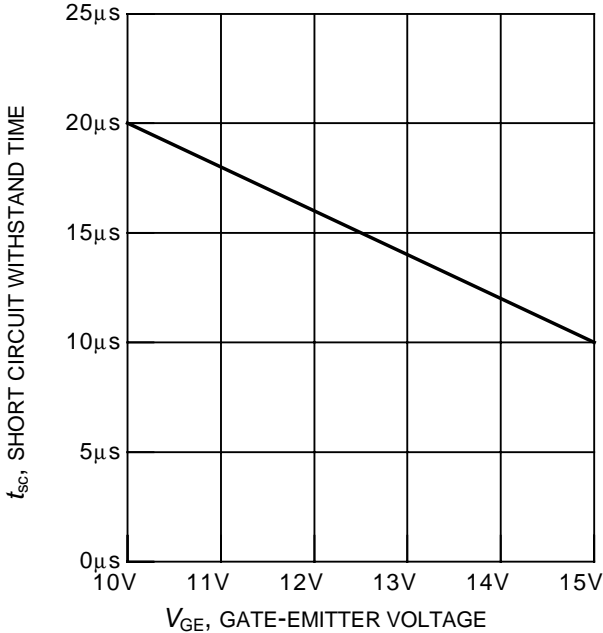
**Figure 16. IGBT transient thermal impedance as a function of pulse width**  
( $D = t_p / T$ )



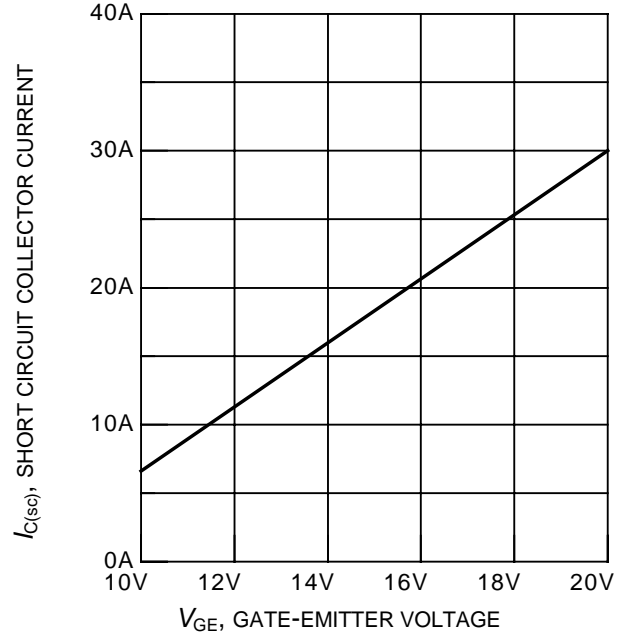
**Figure 17. Typical gate charge**  
( $I_C = 2A$ )



**Figure 18. Typical capacitance as a function of collector-emitter voltage**  
( $V_{GE} = 0V, f = 1MHz$ )



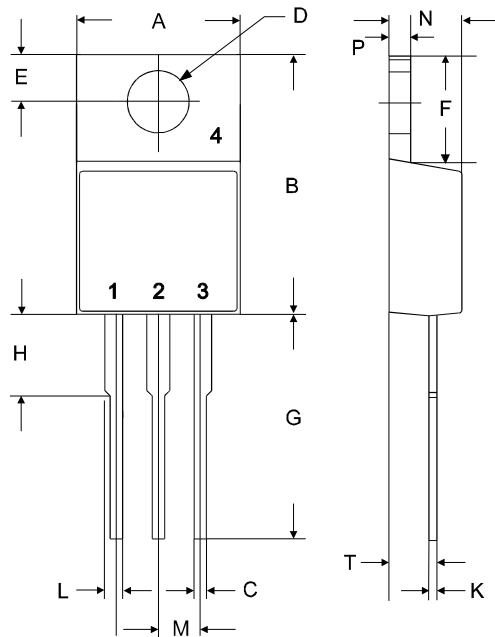
**Figure 19. Short circuit withstand time as a function of gate-emitter voltage**  
( $V_{CE} = 600V, \text{start at } T_j = 25^\circ C$ )



**Figure 20. Typical short circuit collector current as a function of gate-emitter voltage**  
( $V_{CE} \leq 600V, T_j = 150^\circ C$ )

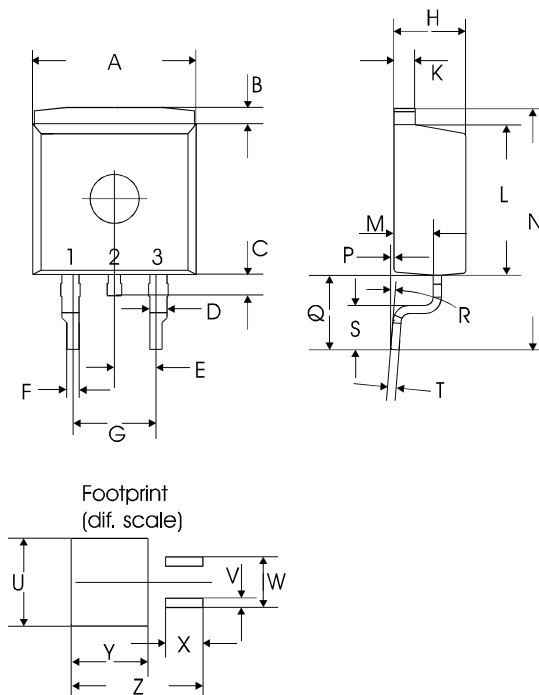


TO-220AB



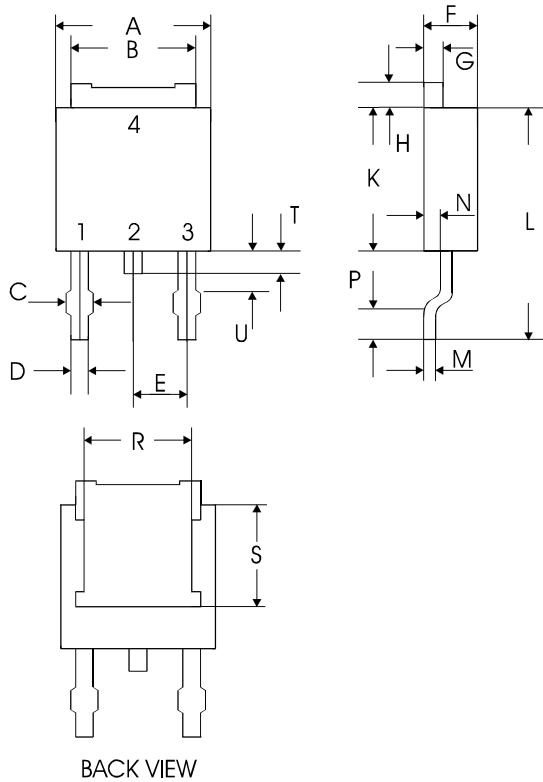
symbol	dimensions			
	[mm]		[inch]	
	min	max	min	max
A	9.70	10.30	0.3819	0.4055
B	14.88	15.95	0.5858	0.6280
C	0.65	0.86	0.0256	0.0339
D	3.55	3.89	0.1398	0.1531
E	2.60	3.00	0.1024	0.1181
F	6.00	6.80	0.2362	0.2677
G	13.00	14.00	0.5118	0.5512
H	4.35	4.75	0.1713	0.1870
K	0.38	0.65	0.0150	0.0256
L	0.95	1.32	0.0374	0.0520
M	2.54 typ.		0.1 typ.	
N	4.30	4.50	0.1693	0.1772
P	1.17	1.40	0.0461	0.0551
T	2.30	2.72	0.0906	0.1071

TO-263AB (D<sup>2</sup>Pak)



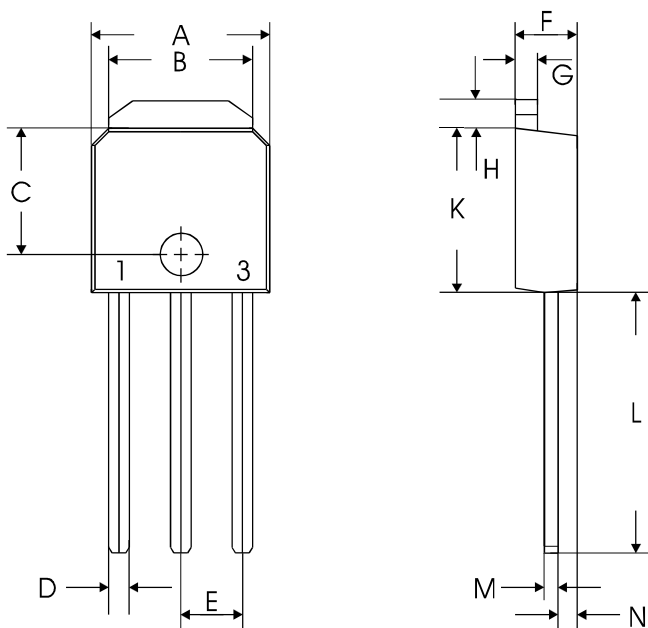
symbol	dimensions			
	[mm]		[inch]	
	min	max	min	max
A	9.80	10.20	0.3858	0.4016
B	0.70	1.30	0.0276	0.0512
C	1.00	1.60	0.0394	0.0630
D	1.03	1.07	0.0406	0.0421
E	2.54 typ.		0.1 typ.	
F	0.65	0.85	0.0256	0.0335
G	5.08 typ.		0.2 typ.	
H	4.30	4.50	0.1693	0.1772
K	1.17	1.37	0.0461	0.0539
L	9.05	9.45	0.3563	0.3720
M	2.30	2.50	0.0906	0.0984
N	15 typ.		0.5906 typ.	
P	0.00	0.20	0.0000	0.0079
Q	4.20	5.20	0.1654	0.2047
R	8° max		8° max	
S	2.40	3.00	0.0945	0.1181
T	0.40	0.60	0.0157	0.0236
U	10.80		0.4252	
V	1.15		0.0453	
W	6.23		0.2453	
X	4.60		0.1811	
Y	9.40		0.3701	
Z	16.15		0.6358	

P-TO252 (D-Pak)



symbol	dimensions			
	[mm]		[inch]	
	min	max	min	max
A	6.40	6.73	0.2520	0.2650
B	5.25	5.50	0.2067	0.2165
C	(0.65)	(1.15)	(0.0256)	(0.0453)
D	0.63	0.89	0.0248	0.0350
E	2.28		0.2520	
F	2.19	2.39	0.0862	0.0941
G	0.76	0.98	0.0299	0.0386
H	0.90	1.21	0.0354	0.0476
K	5.97	6.23	0.2350	0.2453
L	9.40	10.40	0.3701	0.4094
M	0.46	0.58	0.0181	0.0228
N	0.87	1.15	0.0343	0.0453
P	0.51	-	0.0201	-
R	5.00	-	0.1969	-
S	4.17	-	0.1642	-
T	0.26	1.02	0.0102	0.0402
U	-	-	-	-

P-TO251 (I-Pak)



symbol	dimensions			
	[mm]		[inch]	
	min	max	min	max
A	6.47	6.73	0.2547	0.2650
B	5.25	5.41	0.2067	0.2130
C	4.19	4.43	0.1650	0.1744
D	0.63	0.89	0.0248	0.0350
E	2.29 typ.		0.0902 typ.	
F	2.18	2.39	0.0858	0.0941
G	0.76	0.86	0.0299	0.0339
H	1.01	1.11	0.0398	0.0437
K	5.97	6.23	0.2350	0.2453
L	9.14	9.65	0.3598	0.3799
M	0.46	0.56	0.0181	0.0220
N	0.98	1.15	0.0386	0.0453

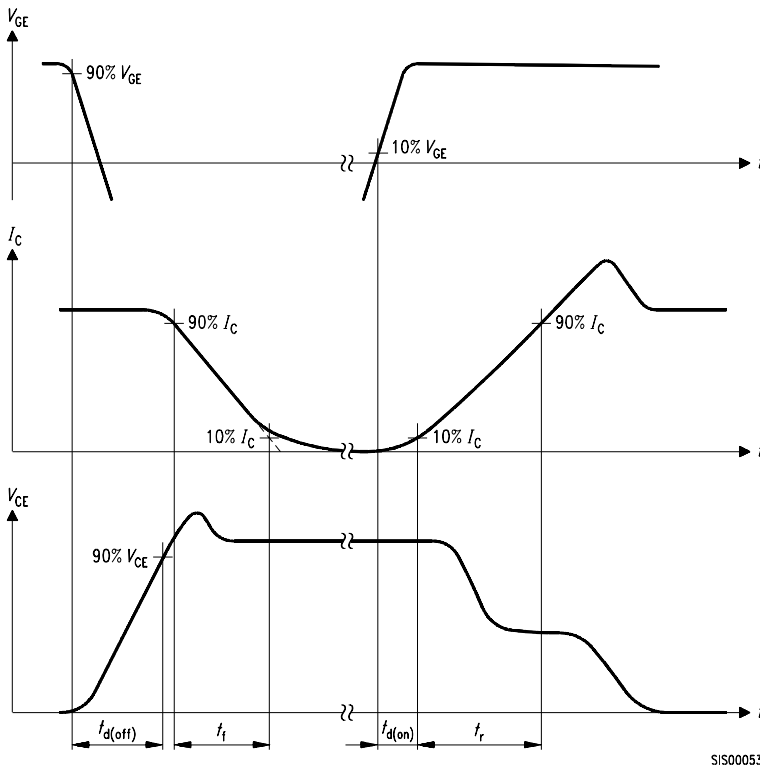


Figure A. Definition of switching times

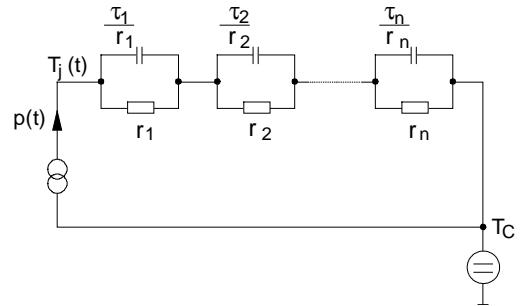


Figure D. Thermal equivalent circuit

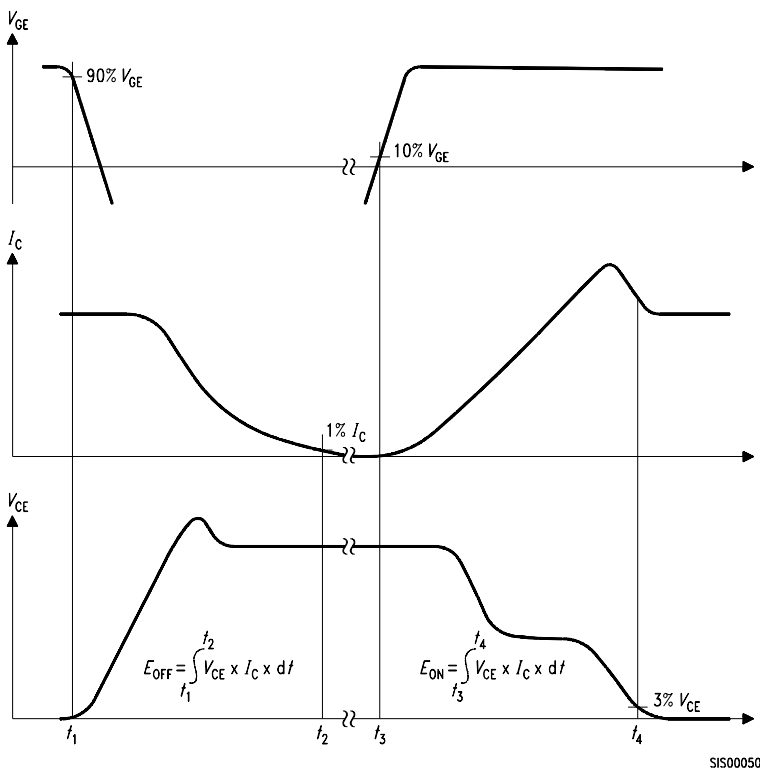


Figure B. Definition of switching losses

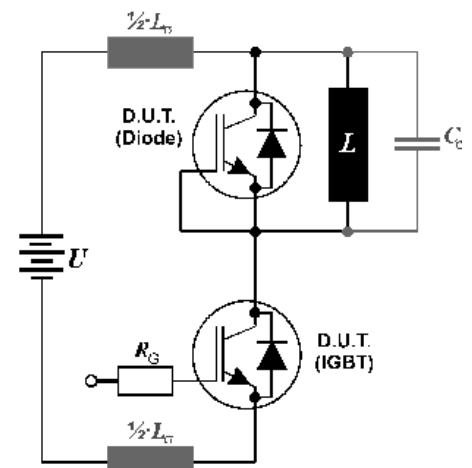


Figure E. Dynamic test circuit  
Leakage inductance  $L_{\sigma} = 180\text{nH}$   
and Stray capacity  $C_{\sigma} = 180\text{pF}$ .

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